Product / Package Information

Package	LFCSP - Punched, Stacked Die
Body Size (mm)	10 X 10 X 0.85 (5.3 EP)
Lead Count	72
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.16E-01	86.91	869100	35.26	352608
Thermosets	Epoxy & Phenol Resin	Proprietary	1.71E-02	12.78	127800	5.19	51851
Other inorganic materials	Carbon black	1333-86-4	4.15E-04	0.31	3100	0.13	1258
Subtotal			1.34E-01	100.00	1000000	40.57	405716

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.76 E-01	97.50	975000	53.35	533530
Copper & its alloys	Iron	7439-89-6	4.25 E-03	2.35	23500	1.29	12859
Copper & its alloys	Zinc	7440-66-6	2.17 E-04	0.12	1200	0.07	657
Copper & its alloys	Phosphorus	7723-14-0	5.42 E-05	0.03	300	0.02	164
Subtotal			1.81 E-01	100.00	1000000	54.72	547210

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.81 E-04	100.0	1000000	0.05	547

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	3.07 E-03	100.0	1000000	0.93	9291

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.43 E-03	100.0	1000000	0.43	4335

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	9.36 E-03	100.0	1000000	2.83	28350

Die Attach 1

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	7.68 E-05	73.54	735400	0.02	233
Other organic materials	Epoxy resin A	TS ref# 10013	7.68 E-06	7.35	73500	0.002	23
Others	Anhydride	TS ref# 10181	7.68 E-06	7.35	73500	0.002	23
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	3.07 E-06	2.94	29400	0.001	9
Other organic materials	Epoxy resin B	TS ref# 10237	3.07 E-06	2.94	29400	0.001	9
Others	Epoxy resin modifier	TS ref# 10038	3.07 E-06	2.94	29400	0.001	9
Others	Anhydride	TS ref# 10180	3.07 E-06	2.94	29400	0.001	9
Subtotal			1.05 E-04	100.0	1000000	0.03	317

Die Attach 2

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Resin	Proprietary	6.99 E-04	50.0	500000	0.21	2117
Other organic materials	Ethene, tetrafluoro-,homopolymer	9002-84-0	6.29 E-04	45.0	450000	0.19	1905
Other organic materials	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8	6.99 E-05	5.0	50000	0.02	212
Subtotal			1.40 E-03	100.0	1000000	0.42	4234

	Weight (g)	Percentage (%)	PPM
Package Totals	**3.30 E-01**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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